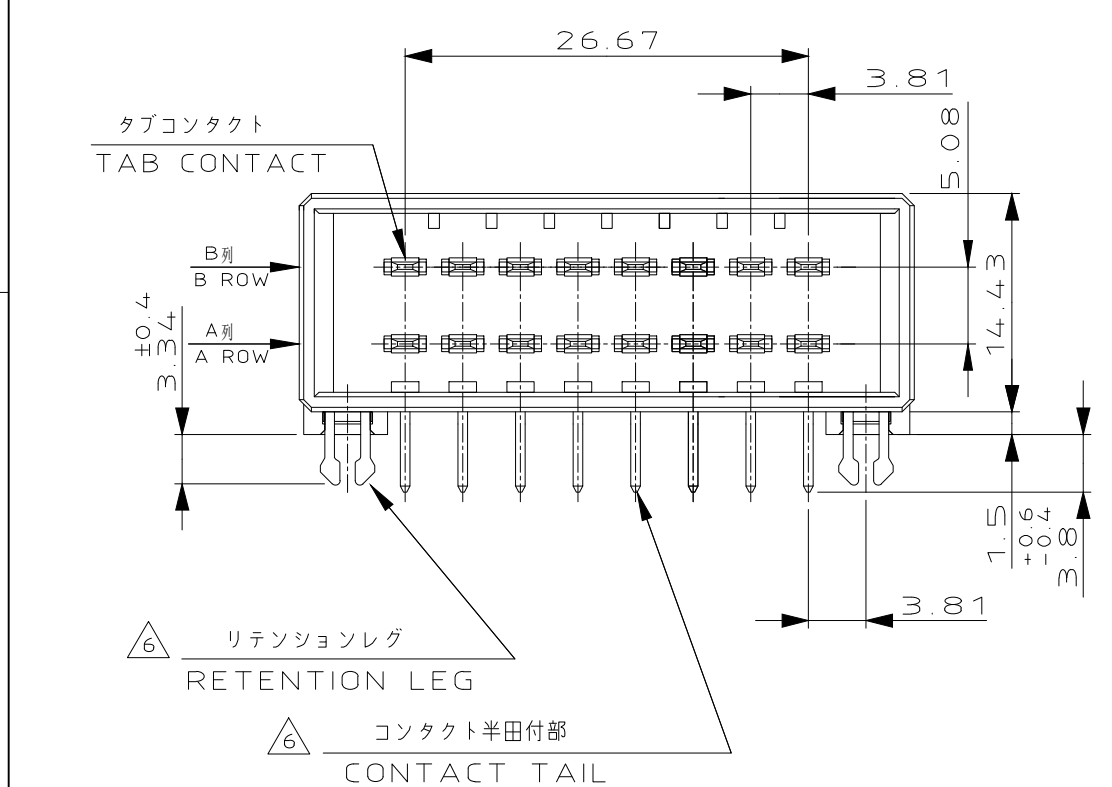
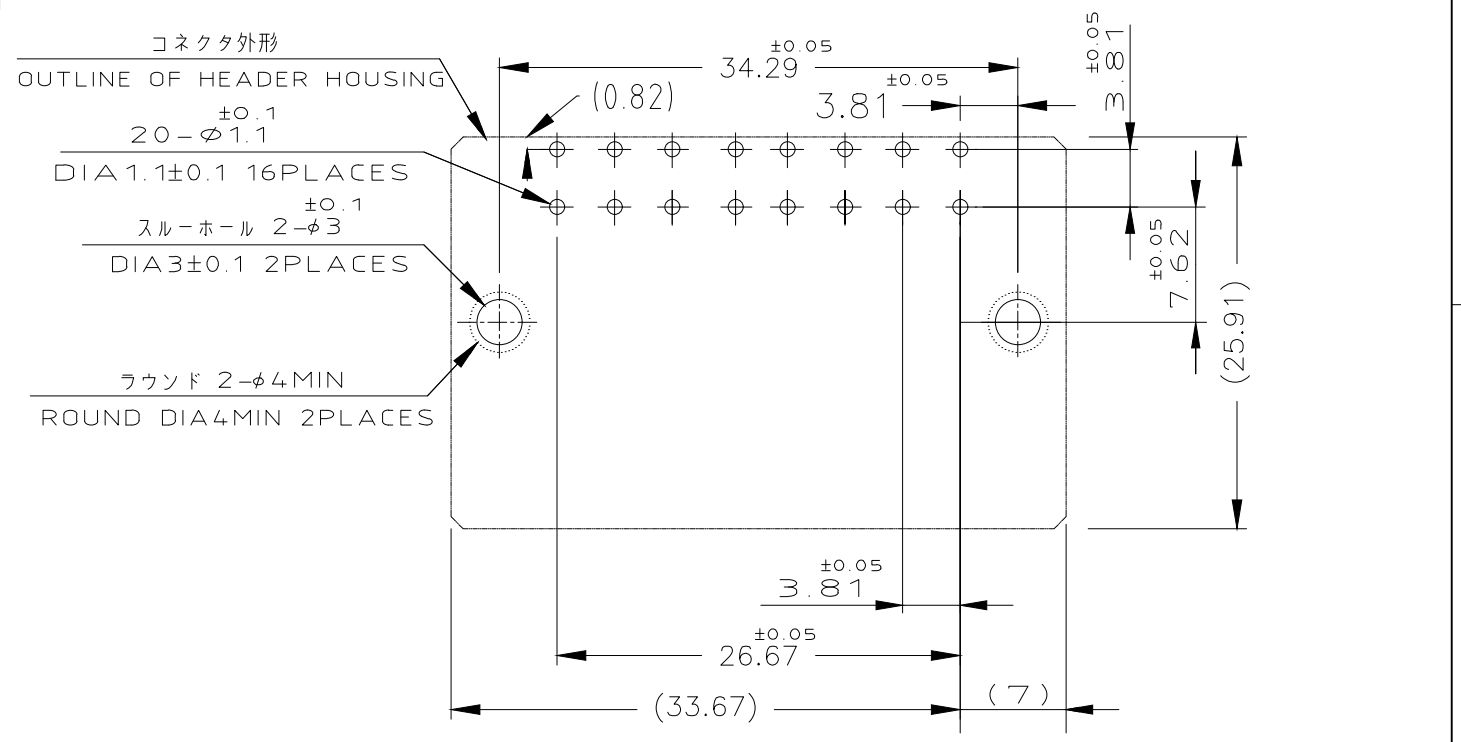
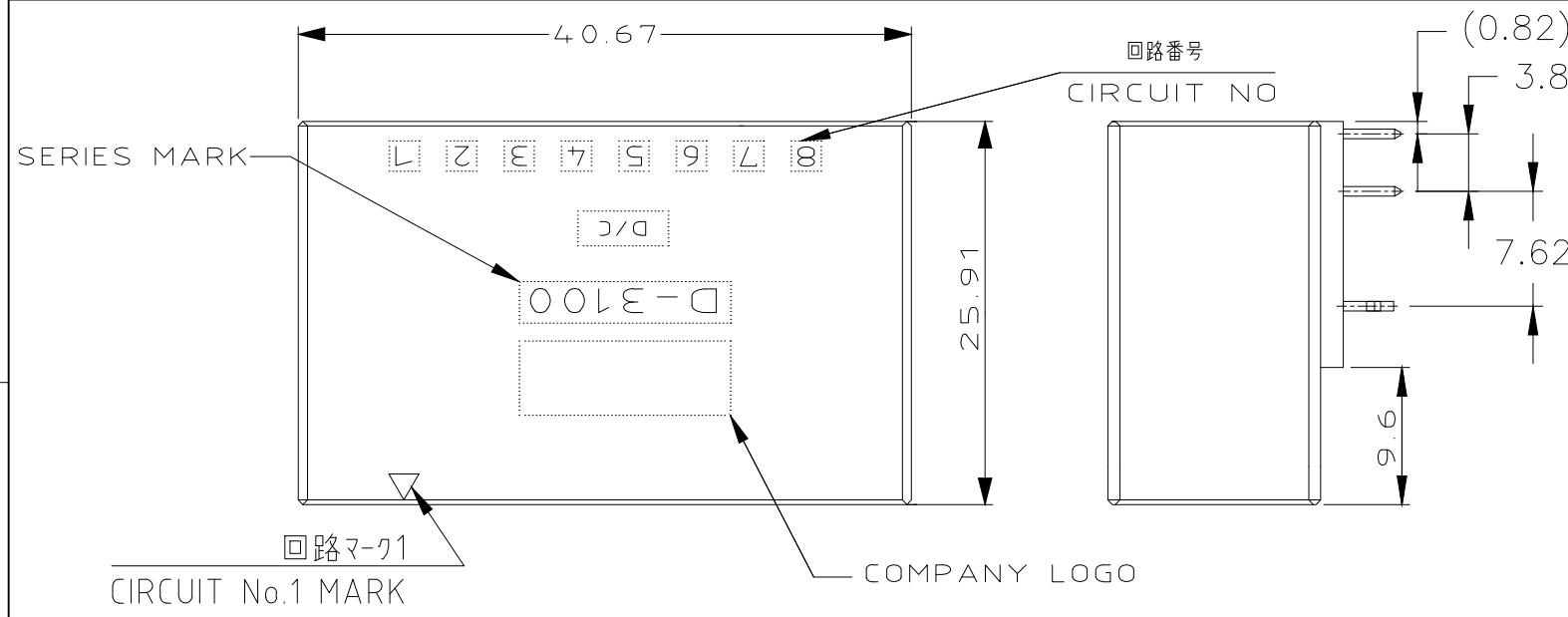


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REVISIONS					
P	LTR	DESCRIPTION	DATE	DWN	APVD
	D2	REVISED PER ECR-18-004413	23MAR2018	K.T	E.I



推奨基板取付け穴寸法  
 PC 基板厚: 1.6 ± 0.1 (非累積公差) (コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN  
 PC BOARD THICKNESS: 1.6 ± 0.1 (NOT ACCUMULATE TOLERANCE) (CONNECTOR MOUNT SIDE)

NOTES

- MATERIAL: HOUSING: GLASS FILED THERMO PLASTIC, POLYESTER COLOR: BLACK  
 CONTACT: COPPER ALLOY  
 RETENTION LEG: COPPER ALLOY
- FINISH (CONTACT AREA): 0.38 μm MIN GOLD PLATING OVER Ni PLATING
- FINISH (CONTACT AREA): 0.76 μm MIN GOLD PLATING OVER Ni PLATING
- FINISH (CONTACT AREA): 2.0 μm MIN TIN PLATED OVER NICKEL
- FINISH (RETENTION LEG): TIN-LEAD PLATED (CONTACT TAIL) OVER NICKEL
- FINISH (RETENTION LEG): TIN PLATED (CONTACT TAIL) OVER NICKEL
- GENERAL TOLERANCE  
 10 ≥ : ±0.3  
 30 ≥ > 10 : ±0.4  
 100 ≥ > 30 : ±0.45  
 ANGLE : ±3°

注記

- 材料: ハウジング: ガラス入り熱可塑性ポリエステル樹脂 色: 黒  
 コンタクト: 銅合金  
 リテンションレグ: 銅合金
- めっき: コンタクト: 全面Ni下地  
 接触部: 0.38 μm MIN金めっき
- めっき: コンタクト: 全面Ni下地  
 接触部: 0.76 μm MIN金めっき
- めっき: コンタクト: 全面Ni下地  
 接触部: 2.0 μm MINスズめっき
- めっき: リテンションレグとコンタクト半田付部  
 ニッケル下地の上に半田めっき
- めっき: リテンションレグとコンタクト半田付部 : ニッケル下地の上にスズめっき
- 一般公差  
 10 ≥ : ±0.3  
 30 ≥ > 10 : ±0.4  
 100 ≥ > 30 : ±0.45  
 角度 : ±3°

△6	△2	178307-6
△6	△4	178307-5
△6	△3	178307-3
△6	△2	178307-2
(FINISH)		製品番号 (PART NO.)

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN K.IKEDA 16.MAR.95	TE Connectivity Ltd.			
DIMENSIONS: mm		CHK S.Manabe 23.MAR.95				
TOLERANCES UNLESS OTHERWISE SPECIFIED.		APVD K.Ikeda 13.MAR.95	NAME			
		PRODUCT SPEC 108-5349	16 POS DOUBLE ROW HORIZONTAL HDR ASSY FOR DYNAMIC 3100			
MATERIAL SEE NOTE		APPLICATION SPEC 114-5148	SIZE	CAGE CODE	DRAWING NO	RESTRICTED TO
FINISH SEE NOTE		WEIGHT	A3	00779	C=178307	-
CUSTOMER DRAWING			SCALE	SHEET	REV	
			2:1	1 OF 1	D2	